# **LN1361CTR**

## Surface Mounting Chip LED

**GW Type** 

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Power dissipation	$P_{\mathrm{D}}$	60	mW	
Forward current	$I_{\mathrm{F}}$	20	mA	
Pulse forward current *	$I_{FP}$	60	mA	
Reverse voltage	V <sub>R</sub>	4	V	
Operating ambient temperature	T <sub>opr</sub>	-25 to +80	°C	
Storage temperature	T <sub>stg</sub>	-30 to +85	°C	

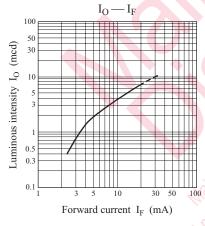
Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

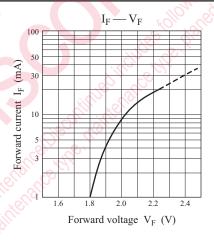
#### ■ Lighting Color

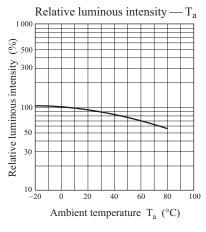
• Yellow Green

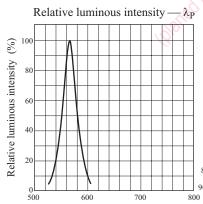
#### ■ Electro-Optical Characteristics $T_a = 25$ °C

Parameter	Symbol		Conditions	Min	Тур	Max	Unit
Luminous intensity	I <sub>O</sub>	$I_F = 20 \text{ mA}$		2.8	7.5	7.5	mcd
Reverse current	$I_R$	$V_R = 4 V$		,,,;;,,	7160,	10	μΑ
Forward voltage	V <sub>F</sub>	$I_F = 20 \text{ mA}$		100,00	2.2	2.8	V
Peak emission wavelength	$\lambda_{\mathrm{P}}$	$I_F = 20 \text{ mA}$	ion,	dille	565		nm
Spectral half band width	Δλ	$I_F = 20 \text{ mA}$	Peir Oni	<i>b</i> .	30		nm

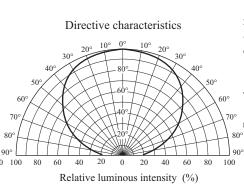


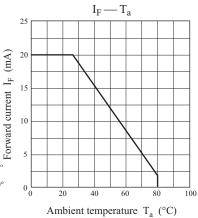






Peak emission wavelength  $\lambda_P$  (nm)

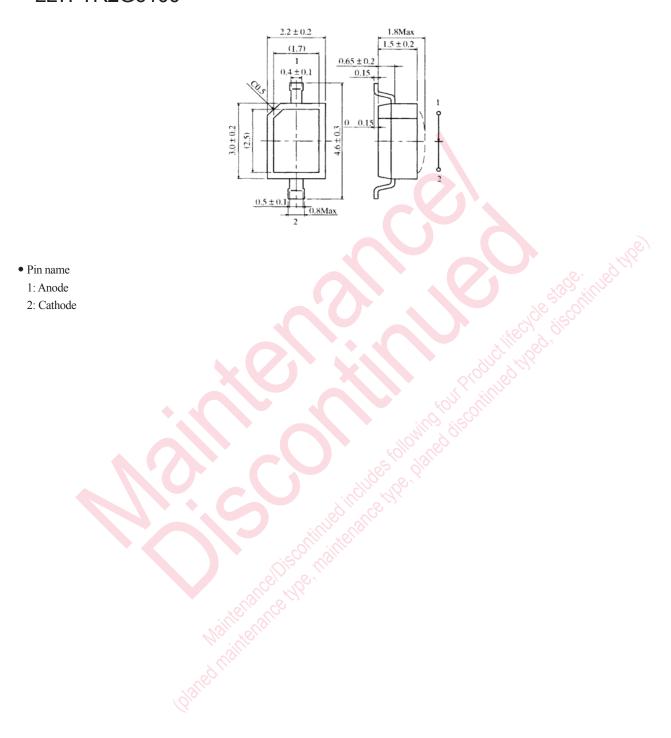




LN1361CTR Panasonic

■ Package (Unit: mm)

## LLTFTR2G6100



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